

DIFFERENTIAL OUTPUT SILICON OSCILLATOR

Features

- Quartz-free, MEMS-free, and PLL-free all-silicon oscillator
- Any output frequencies from 0.9 to 200 MHz
- Short lead times
- Excellent temperature stability (± 20 ppm)
- Highly reliable startup and operation
- High immunity to shock and vibration
- Low jitter: < 1.5 ps rms
- 0 to 85 °C operation includes 10-year aging in hot environments
- Footprint compatible with industry-standard 3.2 x 5.0 mm XOs
- CMOS, SSTL, LVPECL, LVDS, and HCSL versions available
- Driver stopped, tri-state, or powerdown operation
- RoHS compliant
- 1.8, 2.5, or 3.3 V options
- Low power
- More than 10x better fit rate than competing crystal solutions



Specifications

Parameters	Condition	Min	Typ	Max	Units
Frequency Range		0.9	—	200	MHz
Frequency Stability	Temperature stability, 0 to +70 °C	—	± 10	—	ppm
	Temperature stability, 0 to +85 °C	—	± 20	—	ppm
	Total stability, 0 to +70 °C operation ¹	—	—	± 150	ppm
	Total stability, 0 to +85 °C operation ²	—	—	± 250	ppm
Operating Temperature	Commercial	0	—	70	°C
	Extended commercial	0	—	85	°C
Storage Temperature		-55	—	+125	°C
Supply Voltage	1.8 V option	1.71	—	1.98	V
	2.5 V option	2.25	—	2.75	V
	3.3 V option	2.97	—	3.63	V

Notes:

1. Inclusive of 25 °C initial frequency accuracy, operating temperature range, supply voltage change, output load change, first-year aging at 25 °C, shock, vibration, and one solder reflow.
2. Inclusive of 25 °C initial frequency accuracy, operating temperature range, supply voltage change, output load change, ten-year aging at 85 °C, shock, vibration, and one solder reflow.
3. See “AN409: Output Termination Options for the Si500S and Si500D Silicon Oscillators” for further details regarding output clock termination recommendations.
4. $V_{TT} = .5 \times V_{DD}$.
5. $V_{TT} = .45 \times V_{DD}$.

Si500D

Parameters	Condition	Min	Typ	Max	Units
Supply Current	LVPECL	—	34.0	36.0	mA
	Low Power LVPECL	—	19.3	22.2	mA
	LVDS	—	14.9	16.5	mA
	HCSL	—	25.3	29.3	mA
	Differential CMOS(3.3 V option, 10 pF on each output, 200 MHz)	—	33	36	mA
	Differential CMOS(3.3 V option, 1 pF on each output, 40 MHz)	—	16	—	mA
	Differential SSTL-3.3	—	24.5	27.7	mA
	Differential SSTL-2.5	—	24.3	26.7	mA
	Differential SSTL-1.8	—	22.2	25	mA
	Tri-State	—	9.7	10.7	mA
Powerdown	—	1.0	1.9	mA	
Output Symmetry	$V_{DIFF} = 0$	$46 - 13 \text{ ns}/T_{CLK}$	—	$54 + 13 \text{ ns}/T_{CLK}$	%
Rise and Fall Times (20/80%) ³	LVPECL/LVDS	—	—	460	ps
	HCSL/Differential SSTL	—	—	800	ps
	Differential CMOS, 15 pF, ≥ 80 MHz	—	1.1	1.6	ns
LVPECL Output Option (DC coupling, 50 Ω to $V_{DD} - 2.0$ V) ³	Mid-level	$V_{DD} - 1.5$	—	$V_{DD} - 1.34$	V
	Diff swing	.720	—	.880	V_{PK}
Low Power LVPECL Output Option (AC coupling, 100 Ω Differential Load) ³	Mid-level	—	N/A	—	V
	Diff swing	.68	—	.95	V_{PK}
LVDS Output Option (2.5/3.3 V) ($R_{TERM} = 100 \Omega$ diff) ³	Mid-level	1.15	—	1.26	V
	Diff swing	0.25	—	0.45	V_{PK}
LVDS Output Option (1.8 V) ($R_{TERM} = 100 \Omega$ diff) ³	Mid-level	0.85	—	0.96	V
	Diff swing	0.25	—	0.45	V_{PK}
HCSL Output Option ³	Mid-level	0.35	—	0.425	V
	Diff swing	0.65	—	0.82	V_{PK}
	DC termination per pad	45	—	55	Ω
CMOS Output Voltage ³	V_{OH} , sourcing 9 mA	$V_{DD} - 0.6$	—	—	V
	V_{OL} , sinking 9 mA	—	—	0.6	V
SSTL-1.8 Output Voltage ⁴	V_{OH}	$V_{TT} + 0.375$	—	—	V
	V_{OL}	—	—	$V_{TT} - 0.375$	V
SSTL-2.5 Output Voltage ⁴	V_{OH}	$V_{TT} + 0.48$	—	—	V
	V_{OL}	—	—	$V_{TT} - 0.48$	V
SSTL-3.3 Output Voltage ⁵	V_{OH}	$V_{TT} + 0.48$	—	—	V
	V_{OL}	—	—	$V_{TT} - 0.48$	V
Powerup Time	From time V_{DD} crosses min spec supply	—	—	2	ms
OE Deassertion to Clk Stop		—	—	$250 + 3 \times T_{CLK}$	ns
Return from Output Driver Stopped Mode		—	—	$250 + 3 \times T_{CLK}$	ns
Return From Tri-State Time		—	—	$12 + 3 \times T_{CLK}$	μ s

Notes:

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2. Inclusive of 25 °C initial frequency accuracy, operating temperature range, supply voltage change, output load change, ten-year aging at 85 °C, shock, vibration, and one solder reflow.
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Parameters	Condition	Min	Typ	Max	Units
Return From Powerdown Time		—	—	2	ms
Period Jitter (1-sigma)	Non-CMOS	—	1	2	ps RMS
	CMOS, $C_L = 7$ pF	—	1	3	ps RMS
Integrated Phase Jitter	1.0 MHz – min(20 MHz, 0.4 x F_{OUT}), non-CMOS	—	0.6	1	ps RMS
	1.0 MHz – min(20 MHz, 0.4 x F_{OUT}), CMOS format	—	0.7	1.5	ps RMS

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3. See “AN409: Output Termination Options for the Si500S and Si500D Silicon Oscillators” for further details regarding output clock termination recommendations.
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Si500D

Package Specifications



Table 1. Package Diagram Dimensions (mm)

Dimension	Min	Nom	Max
A	0.80	0.85	0.90
A1	0.00	0.03	0.05
b	0.59	0.64	0.69
D	3.20 BSC.		
e	1.27 BSC.		
E	4.00 BSC.		
L	0.95	1.00	1.05

Dimension	Min	Nom	Max
L1	0.00	0.05	0.10
aaa	—	—	0.10
bbb	—	—	0.10
ccc	—	—	0.08
ddd	—	—	0.10
eee	—	—	0.05

Table 2. Pad Connections

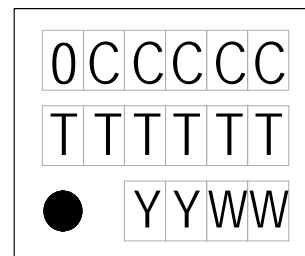
1	OE
2	NC—Make no external connection to this pin
3	GND
4	Output
5	Complementary Output
6	VDD

Table 3. Tri-State/Powerdown/Driver Stopped Function on OE (3rd Option Code)

	A	B	C	D	E	F
Open	Active	Active	Active	Active	Active	Active
1 Level	Active	Tri-State	Active	Power-down	Active	Driver Stopped
0 Level	Tri-State	Active	Power-down	Active	Driver Stopped	Active



Figure 1. Recommended Land Pattern



0 = Si500
 CCCCC = mark code
 TTTTTT = assembly manufacturing code
 YY = year
 WW = work week

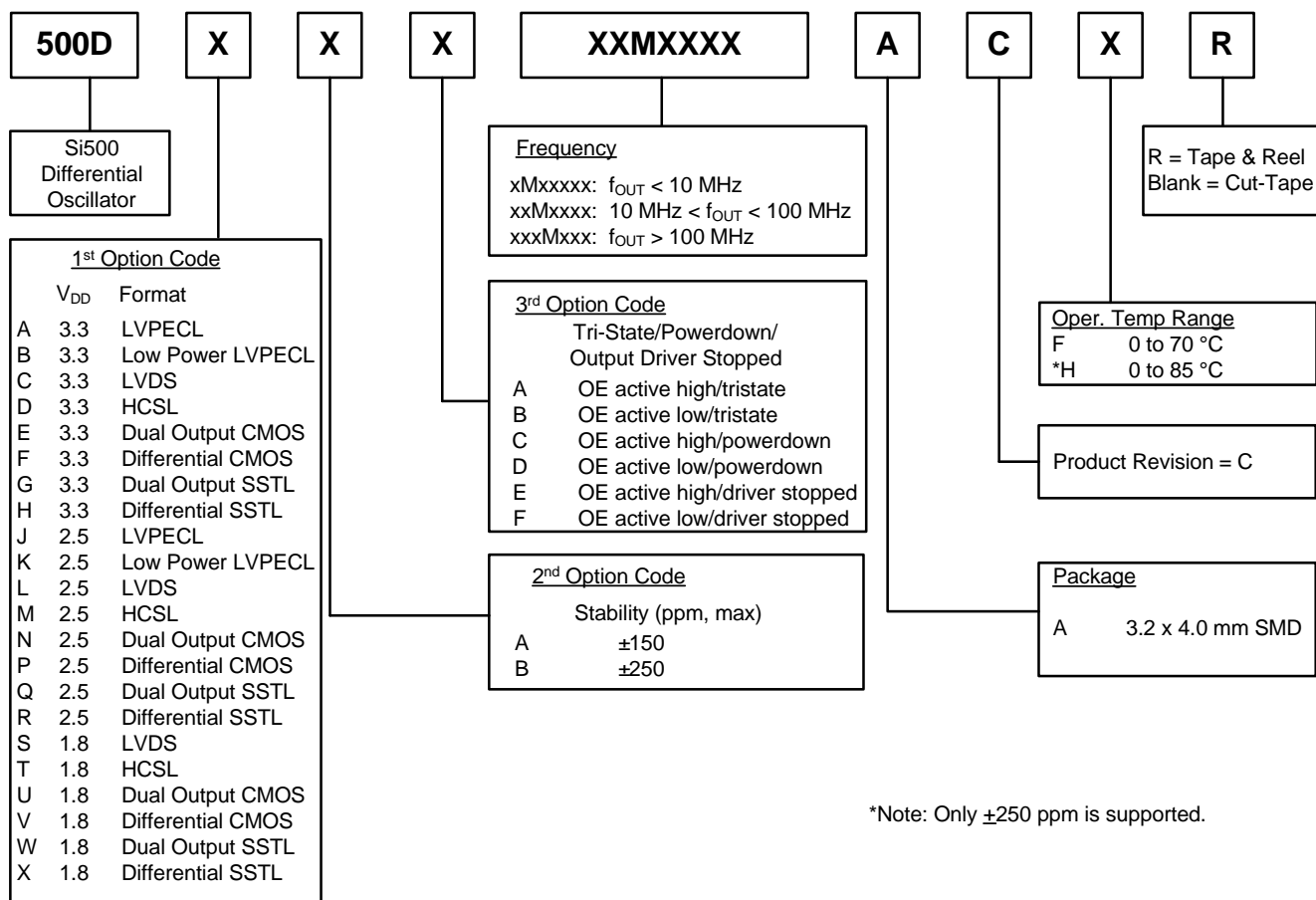
Figure 2. Top Mark

Environmental Compliance

Parameter	Conditions/Test Method
Mechanical Shock	MIL-STD-883, Method 2002.4
Mechanical Vibration	MIL-STD-883, Method 2007.3 A
Resistance to Soldering Heat	MIL-STD-202, 260 C° for 8 seconds
Solderability	MIL-STD-883, Method 2003.8
Damp Heat	IEC 68-2-3
Moisture Sensitivity Level	J-STD-020, MSL 3

Ordering Information

The Si500D supports a variety of options including frequency, output format, supply voltage, and tri-state/powerdown. Specific device configurations are programmed into the Si500D at time of shipment. Configurations are specified using the figure below. Silicon Labs provides a web-based part number utility that can be used to simplify part number configuration. Refer to www.silabs.com/SiliconXOPartnumber to access this tool. The Si500D XO series is supplied in a ROHS-compliant, Pb-free, 6-pad, 3.2 x 4.0 mm package. Tape and reel packaging is available as an ordering option.



DOCUMENT CHANGE LIST

Revision 0.2 to Revision 0.3

- Revision B to Revision C updated in Ordering Information
- 0 to 85 °C Operating Temperature Range option added

Revision 0.3 to Revision 1.0

- Clarified SSTL specifications.
- Revised Differential CMOS supply current values.
- Clarified Differential CMOS supply current loading conditions.

Revision 1.0 to Revision 1.1

- Updated Ordering information for ± 250 ppm from 0 to +85 °C.
- Updated jitter from 1.5 ps to 1.5 ps rms.
- Updated operating temperature to include extended commercial at 0 to +85 °C.
- Updated features to include LVPECL, LVDS, and HCSL.



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Silicon Laboratories Inc.
400 West Cesar Chavez
Austin, TX 78701
USA

<http://www.silabs.com>

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- Оценку стоимости проекта по компонентам.
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Тел: +7 (812) 336 43 04 (многоканальный)
Email: org@lifeelectronics.ru